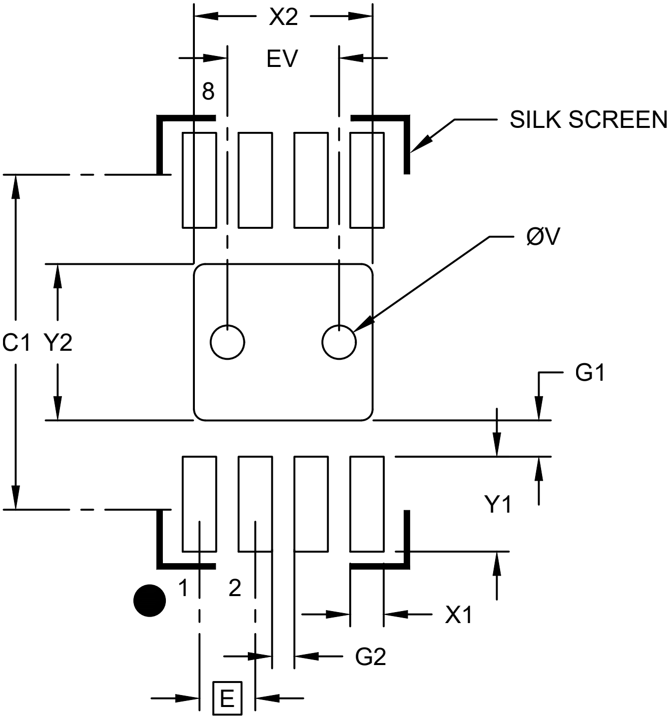
8-Lead Very Thin Plastic Dual Flat, No Lead Package (MWF) - 2x3x1.0 mm Body [VDFN] 1.5x1.3 mm Exposed Pad Wettable Step Cut Flanks

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
		Dimension Limits	MIN	NOM	MAX
Contact Pitch	E			0.50 BSC	
Center Pad Width	X2				1.60
Center Pad Length	Y2				1.40
Contact Pad Spacing	C1			2.90	
Contact Pad Width (X8)	X1				0.30
Contact Pad Length (X8)	Y1				0.85
Contact Pad to Center Pad (X8)	G1		0.33		
Contact Pad to Contact Pad (X6)	G2		0.20		
Thermal Via Diameter	V			0.30	
Thermal Via Pitch	EV			1.00	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process